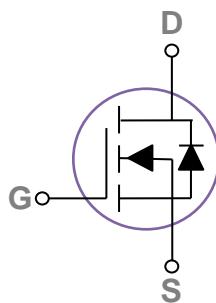


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### SOT23-3S Pin Configuration



BVDSS	RDS(ON)	ID
30V	24mΩ	6.5A

### Features

- 30V, 6.5A, RDS(ON) = 24mΩ @ VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- MB / VGA / Vcore
- Load Switch
- Hand-Held Instrument

### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>Ds</sub>	Drain-Source Voltage	30	V
V <sub>Gs</sub>	Gate-Source Voltage	$\pm 20$	V
I <sub>D</sub>	Drain Current – Continuous ( $T_A=25^\circ\text{C}$ )	6.5	A
	Drain Current – Continuous ( $T_A=100^\circ\text{C}$ )	4.1	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	26	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	32	mJ
I <sub>AS</sub>	Single Pulse Avalanche Current <sup>2</sup>	8	A
P <sub>D</sub>	Power Dissipation ( $T_c=25^\circ\text{C}$ )	1.56	W
	Power Dissipation – Derate above 25°C	0.012	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	80	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.04	---	$\text{V}/^\circ\text{C}$
$I_{\text{DS}}^{\text{SS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>3</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=6\text{A}$	---	20	24	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=4\text{A}$	---	27	34	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D = 250\mu\text{A}$	1.2	1.6	2.5	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	-4	---	$\text{mV}/^\circ\text{C}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_D=4\text{A}$	---	6.5	---	S

**Dynamic and switching Characteristics**

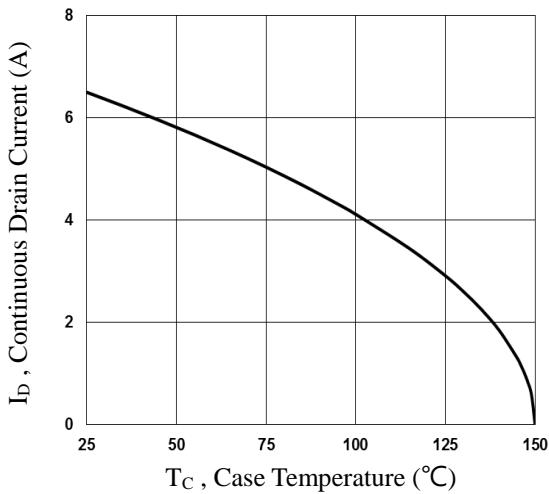
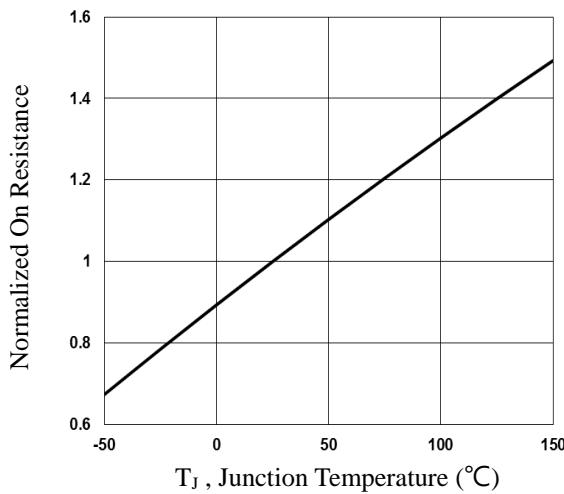
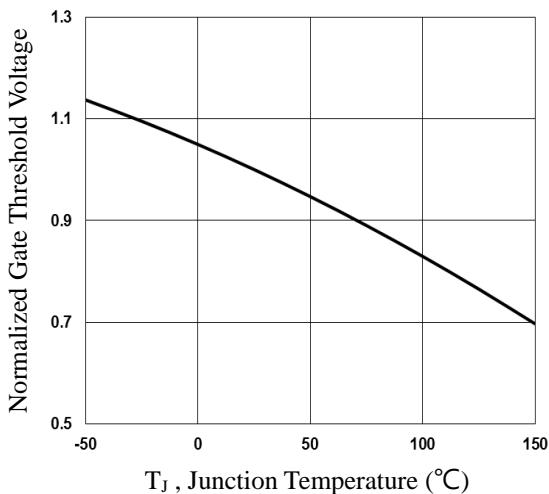
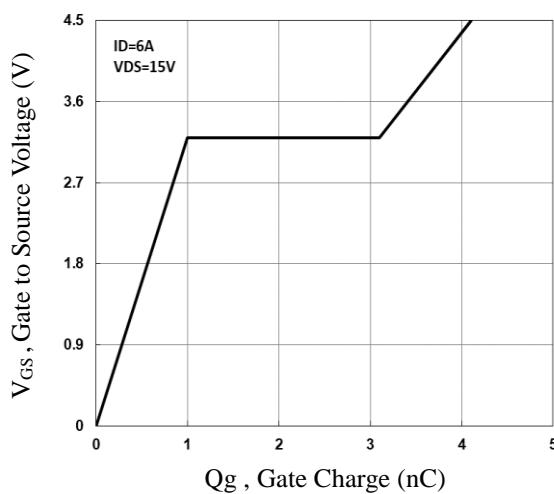
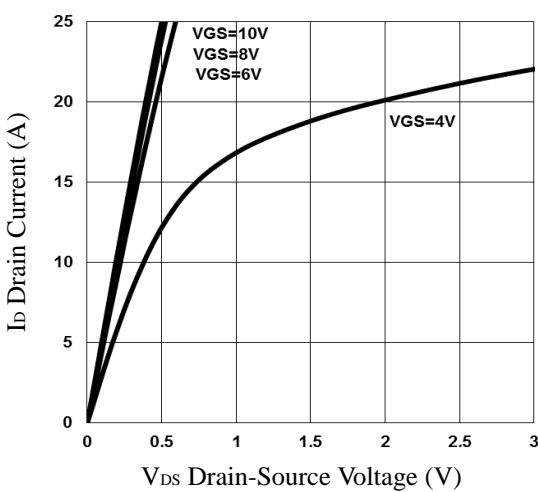
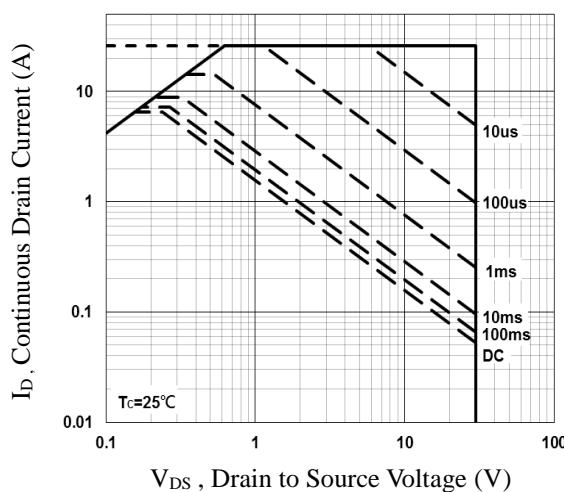
$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $I_D=6\text{A}$	---	4.1	8	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>3, 4</sup>		---	1	2	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>3, 4</sup>		---	2.1	4	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{\text{DD}}=15\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=6\Omega$	---	2.8	5	ns
$T_r$	Rise Time <sup>3, 4</sup>		---	7.2	14	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>3, 4</sup>		---	15.8	30	
$T_f$	Fall Time <sup>3, 4</sup>		---	4.6	9	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	345	500	pF
$C_{\text{oss}}$	Output Capacitance		---	55	80	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	32	45	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$	---	3.2	6.4	$\Omega$

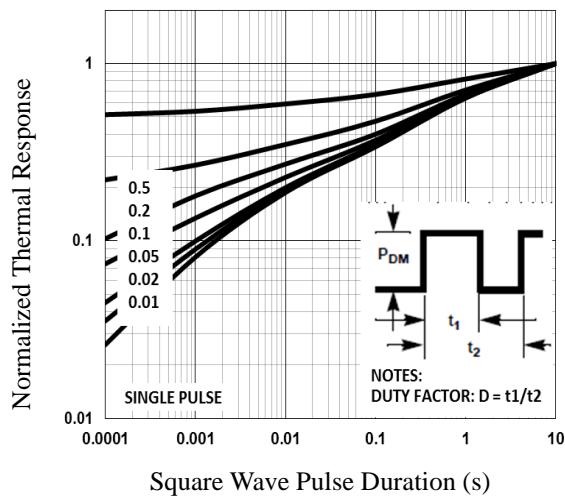
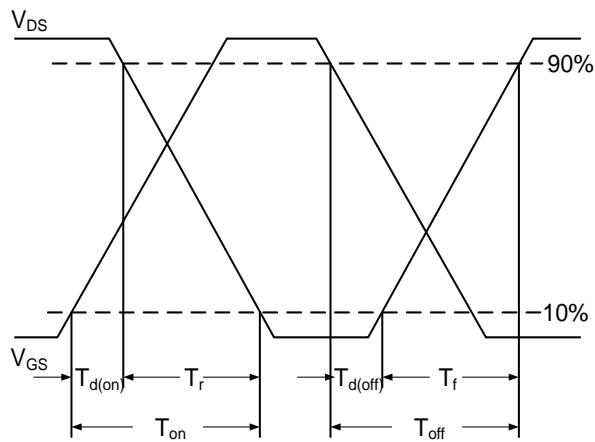
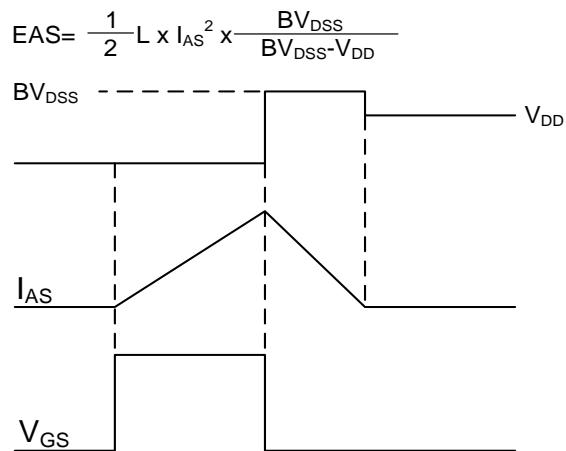
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	6.5	A
$I_{\text{SM}}$	Pulsed Source Current <sup>3</sup>		---	---	26	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>3</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V
$t_{\text{rr}}$	Reverse Recovery Time		---	---	---	ns
$Q_{\text{rr}}$	Reverse Recovery Charge	$T_J=25^\circ\text{C}$	---	---	---	nC

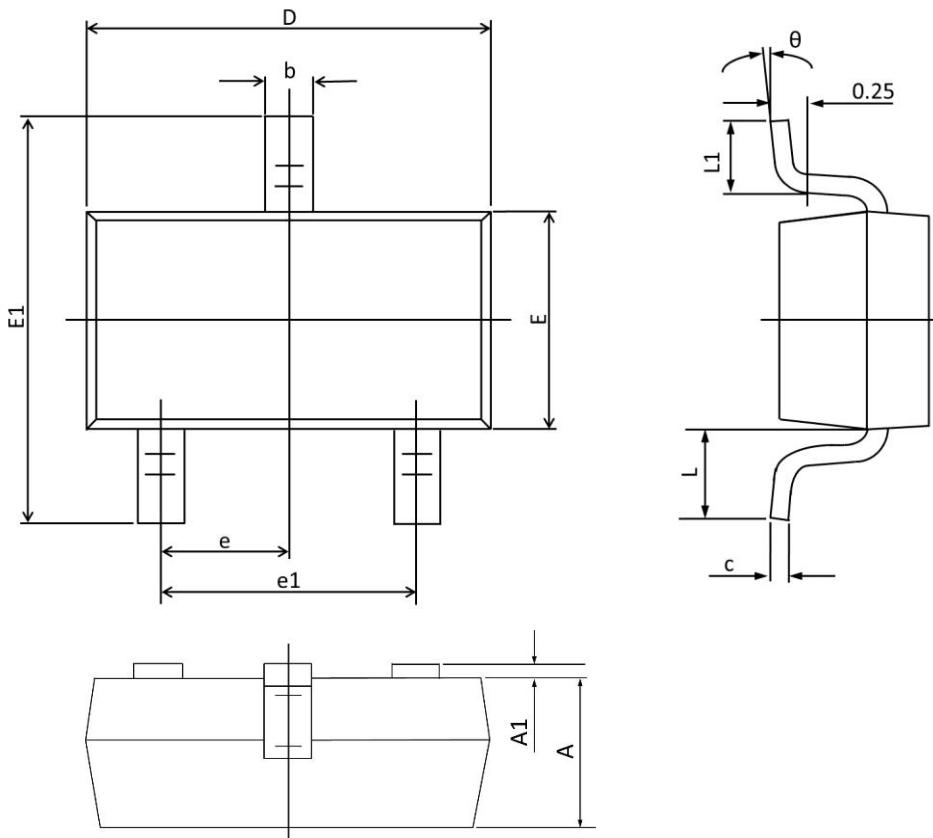
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=1\text{mH}$ ,  $I_{\text{AS}}=8\text{A}$ ,  $R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
3. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs. TC**

**Fig.2 Normalized RDSON vs. TJ**

**Fig.3 Normalized Vth vs. TJ**

**Fig.4 Gate Charge Waveform**

**Fig.5 On Region Characteristics**

**Fig.6 Maximum Safe Operation Area**


**Fig.7 Normalized Transient Response**

**Fig.8 Switching Time Waveform**

**Fig.9 EAS Waveform**

## SOT23-3S PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.001	0.100	0.000	0.004
b	0.300	0.500	0.012	0.020
c	0.080	0.180	0.003	0.008
D	2.700	3.100	0.106	0.122
E	1.100	1.500	0.043	0.059
E1	2.100	2.640	0.080	0.104
e	0.950 TYP.		0.037 TYP.	
e1	1.780	2.040	0.070	0.080
L	0.550 REF.		0.022 REF.	
L1	0.100	0.500	0.004	0.020
θ	1°	10°	1°	10°